

THE RIAC 217PLUS™ SWITCH AND RELAY FAILURE RATE MODELS

David Nicholls, RIAC (Quanterion Solutions Incorporated)

In a previous edition of the RIAC Journal [Reference 1], we provided a high-level introduction to the 217Plus™ component failure rate prediction models, and in the last three editions we presented the 217Plus™ capacitor and diode failure rate models [Reference 2], the integrated circuit and inductor failure rate models [Reference 3], and the transformer and optoelectronic device models [Reference 4].

In this edition of the Journal, we present the Switch and Relay component models in their entirety. A brief example will be provided at the end of the article.

217Plus™ Switch Failure Rate Model

The failure rate equation for switches [Reference 5] is:

$$\lambda_p = \pi_G (\lambda_{OB} \pi_{DCO} \pi_{TO} + \lambda_{EB} \pi_{DCN} \pi_{TE} + \lambda_{TCB} \pi_{CR} \pi_{DT}) + \lambda_{IND}$$

where,

λ_p = Predicted failure rate, failures per million calendar hours

π_G = Reliability growth failure rate multiplier:

$$\pi_G = e^{(-\beta(Y - 1993))}$$

β = Growth constant. Function of switch type (see Table 1)

λ_{OB} = Base failure rate, operating. Function of switch type (see Table 1)

π_{DCO} = Failure rate multiplier for duty cycle, operating:

$$\pi_{DCO} = \frac{DC}{DC_{1op}}$$

DC_{1op} = Constant. Function of switch type (see Table 1)

π_{TO} = Failure rate multiplier for temperature, operating:

$$\pi_{TO} = e^{\left(\frac{-Ea_{op}}{0.00008617} \left(\frac{1}{T_{AO} + T_R + 273} - \frac{1}{298}\right)\right)}$$

Ea_{op} = Activation energy, operating. Function of switch type (see Table 1).

T_R = The junction temperature rise above the ambient operating temperature (T_{AO}). The junction temperature is, therefore, $T_{AO} + T_R$. T_R can be determined in several ways:

$T_{Rdefault}$ = Default temperature rise (see Table 1)

T_R = Actual (measured) temperature rise, if known

λ_{EB} = Base failure rate, environmental (see Table 1)

π_{DCN} = Failure rate multiplier, duty cycle – nonoperating:

$$\pi_{DCN} = \frac{1 - DC}{DC_{1nonop}}$$

DC_{1nonop} = Constant. Function of switch type (see Table 1)

π_{TE} = Failure rate multiplier, temperature:

$$\pi_{TE} = e^{\left(\frac{-Ea_{nonop}}{0.00008617} \left(\frac{1}{T_{AE} + 273} - \frac{1}{298}\right)\right)}$$

Ea_{nonop} = Activation energy, nonoperating. Function of transformer type (see Table 1)

λ_{TCB} = Base failure rate, temperature cycling (see Table 1)

π_{CR} = Failure rate multiplier, cycling rate:

$$\pi_{CR} = \frac{CR}{CR_1}$$

CR_1 = Constant. Function of switch type (see Table 1)

π_{DT} = Failure rate multiplier, delta temperature:

$$\pi_{DT} = \left(\frac{T_{AO} + T_R - T_{AE}}{DT_1}\right)^2$$

DT_1 = Constant. Function of switch type
(see Table 1)

λ_{IND} = Failure rate, electrical overstress (see Table 1)

NOTE: Environment-type and equipment-dependent default values for DC, T_{AO} , T_{AE} and CR were previously presented in Reference 1, where,

DC = Duty cycle (the percent of calendar time that the system in which the component is operating is in an operational state)

T_{AO} = Ambient temperature, operating
(in degrees C)

T_{AE} = Ambient temperature, nonoperating
(in degrees C)

CR = Cycling rate (the number of power cycles per year to which the system is exposed). In this case, it is assumed that the system transitions from a nonoperating environment to an operating environment at the same time that the power is applied.

Table 1: Switch Parameters

Part Type	λ_{OB}	λ_{EB}	λ_{TCB}	λ_{IND}	β	DC _{Top}	Ea _{op}	T _{Rdefault}	DC _{Inonop}	Ea _{Inonop}	CR ₁	DT ₁
Centrifugal	0.1763992	24.3578773	1.1371796	1.3841695	0	0.54	1.0	0	0.46	1.0	520	27.52
Coaxial	0.0108773	0.3389856	0.0619184	0.0145728	0	0.54	1.0	0	0.46	1.0	520	27.52
DIP	0.0008827	0.0026479	0.0035170	0.0003568	0	0.54	1.0	0	0.46	1.0	520	27.52
Float	0.0186419	0.9506430	0.1694149	0.0056024	0	0.54	1.0	0	0.46	1.0	520	27.52
Flow	0.0766708	2.5128573	0.3233836	0.1653016	0	0.54	1.0	0	0.46	1.0	520	27.52
General	0.0633936	2.7259861	0.2610704	0.2151248	0	0.54	1.0	0	0.46	1.0	520	27.52
Humidity	0.1212009	6.1184867	0.6478834	0.2485436	0	0.54	1.0	0	0.46	1.0	520	27.52
Limit	0.0481070	3.7267871	0.4346893	0.1707682	0	0.54	1.0	0	0.46	1.0	520	27.52
Microwave	0.1298078	0.0872547	0.7027604	0.0365085	0	0.54	1.0	0	0.46	1.0	520	27.52
Pressure	0.1199343	9.5751997	0.3924477	0.3608724	0	0.54	1.0	0	0.46	1.0	520	27.52
Push Button	0.0061385	0.8036260	0.0325822	0.0116812	0	0.54	1.0	0	0.46	1.0	520	27.52
Reed	0.0051377	0.2857773	0.0155062	0.0035639	0	0.54	1.0	0	0.46	1.0	520	27.52
Rocker	0.0328250	0.0312763	0.1468059	0.0110910	0	0.54	1.0	0	0.46	1.0	520	27.52
Rotary	1.1377350	2.7045401	2.6269820	0.5794457	0	0.54	1.0	0	0.46	1.0	520	27.52
Sensitive	0.0051602	0.3813068	0.0337622	0.0034288	0	0.54	1.0	0	0.46	1.0	520	27.52
Slide	0.0021569	0.0042558	0.0067203	0.0006768	0	0.54	1.0	0	0.46	1.0	520	27.52
Thermostatic	0.0088297	0.3185724	0.0313801	0.0244460	0	0.54	1.0	0	0.46	1.0	520	27.52
Thumbwheel	0.0181690	0.1479348	0.0334797	0.0224719	0	0.54	1.0	0	0.46	1.0	520	27.52
Toggle	0.0020129	0.1911024	0.0051910	0.0045012	0	0.54	1.0	0	0.46	1.0	520	27.52
Wave Guide	0.1871445	4.5453838	1.1776141	0.1846414	0	0.54	1.0	0	0.46	1.0	520	27.52

continued on next page >>>

217Plus™ Relay Failure Rate Model

The failure rate equation for relays [Reference 5] is:

$$\lambda_P = \pi_G (\lambda_{OB} \pi_{DCO} \pi_{TO} + \lambda_{EB} \pi_{DCN} \pi_{TE} + \lambda_{TCB} \pi_{CR} \pi_{DT}) + \lambda_{IND}$$

where,

λ_P = Predicted failure rate, failures per million calendar hours

π_G = Reliability growth failure rate multiplier:

$$\pi_G = e^{(-\beta(Y - 1993))}$$

β = Growth constant. Function of relay type (see Table 2).

λ_{OB} = Base failure rate, operating (see Table 2)

π_{DCO} = Failure rate multiplier for duty cycle, operating:

$$\pi_{DCO} = \frac{DC}{DC_{1op}}$$

DC_{1op} = Constant. Function of relay type (see Table 2)

π_{TO} = Failure rate multiplier for temperature, operating:

$$\pi_{TO} = e^{\left(\frac{-Ea_{op}}{0.00008617} \left(\frac{1}{T_{AO} + T_R + 273} - \frac{1}{298}\right)\right)}$$

Ea_{op} = Activation energy, operating. Function of relay type (see Table 2).

T_R = The junction temperature rise above the ambient operating temperature (T_{AO}). The junction temperature is, therefore, $T_{AO} + T_R$. T_R can be calculated in several ways:

$T_{Rdefault}$ = Default temperature rise (see Table 2)

T_R = Actual temperature rise, if known

λ_{EB} = Base failure rate, environmental (see Table 2)

π_{DCN} = Failure rate multiplier, duty cycle – nonoperating:

$$\pi_{DCN} = \frac{1 - DC}{DC_{1nonop}}$$

DC_{1nonop} = Constant. Function of relay type (see Table 2)

π_{TE} = Failure rate multiplier, temperature:

$$\pi_{TE} = e^{\left(\frac{-Ea_{nonop}}{0.00008617} \left(\frac{1}{T_{AE} + 273} - \frac{1}{298}\right)\right)}$$

Ea_{nonop} = Activation energy, nonoperating. Function of relay type (see Table 2)

λ_{TCB} = Base failure rate, temperature cycling (see Table 2)

π_{CR} = Failure rate multiplier, cycling rate:

$$\pi_{CR} = \frac{CR}{CR_1}$$

CR_1 = Constant. Function of relay type (see Table 2)

π_{DT} = Failure rate multiplier, delta temperature:

$$\pi_{DT} = \left(\frac{T_{AO} + T_R - T_{AE}}{DT_1}\right)^2$$

DT_1 = Constant. Function of relay type (see Table 2)

λ_{IND} = Failure rate, induced (see Table 2)

Table 2: Relay Parameters

Part Type	λ_{OB}	λ_{EB}	λ_{TCB}	λ_{IND}	β	DC_{1op}	Ea_{op}	$T_{Rdefault}$	DC_{1nonop}	Ea_{nonop}	CR_1	DT_1
General Purpose	0.0063446	0.1432385	0.0109744	0.0247443	0	0.51	1.1	0	0.49	1.1	500	22.55
Reed	0.0067468	0.0198698	0.0095525	0.0076172	0	0.51	1.1	0	0.49	1.1	500	22.55
Solid State	0.0000514	0.0015014	0.0000596	0.0002885	0	0.51	1.1	0	0.49	1.1	500	22.55
Thermal	0.0325570	4.8930327	0.0814692	0.4014993	0	0.51	1.1	0	0.49	1.1	500	22.55
Time Delay	0.0130515	0.7657106	0.0185094	0.0788699	0	0.51	1.1	0	0.49	1.1	500	22.55

As with the Switch model, the environment-type and equipment-dependent default values for DC, T_{AO} , T_{AE} and CR were previously presented in Reference 1.

Example Calculation

What is the predicted failure rate of a pressure switch manufactured in 2006. The pressure switch operates in a “Ground, Mobile, Heavy-wheeled” vehicle with an assumed operating temperature of 55°C, a dormant temperature of 14°C and a relative humidity of 40%. The actual temperature rise of the switch is unknown. The operating profile of the equipment is typical of military ground equipment, with a duty cycle of 45% and a cycling rate of 263 cycles per year.

$$\lambda_p = \pi_G (\lambda_{OB} \pi_{DCO} \pi_{TO} + \lambda_{EB} \pi_{DCN} \pi_{TE} + \lambda_{TCB} \pi_{CR} \pi_{DT}) + \lambda_{IND}$$

The failure rate equation for a switch [Reference 5] is:

$$\pi_G = e^{(-\beta(Y-1993))} = 1.0$$

where,

$$\beta = 0 \text{ (from Table 1) and } Y = 2006 \text{ (given)}$$

$$\pi_{DCO} = \frac{DC}{DC_{1op}} = 0.8333$$

$$\lambda_{OB} = 0.1199 \text{ (from Table 1)} \\ DC = 0.45 \text{ (given as 45\%)}$$

$$\pi_{TO} = e^{\left(\frac{-Ea_{op}}{0.00008617} \left(\frac{1}{T_{AO} + 273} - \frac{1}{298}\right)\right)} = 35.23$$

$$DC_{1op} = 0.54 \text{ (from Table 1)} \\ Ea_{op} = 1.0 \text{ (from Table 1)} \\ T_{AO} = 55 \text{ (given)}$$

$$\pi_{DCN} = \frac{1 - DC}{DC_{1nonop}} = 1.196$$

$$\lambda_{EB} = 9.575 \text{ (from Table 1)} \\ DC = 0.45 \text{ (given as 45\%)}$$

$$\pi_{TE} = e^{\left(\frac{-Ea_{nonop}}{0.00008617} \left(\frac{1}{T_{AE} + 273} - \frac{1}{298}\right)\right)} = 0.2248$$

$$DC_{1nonop} = 0.46 \text{ (from Table 1)} \\ Ea_{nonop} = 1.0 \text{ (from Table 1)} \\ T_{AE} = 14 \text{ (given)}$$

$$\pi_{CR} = \frac{CR}{CR_1} = 0.5058$$

$$\lambda_{TCB} = 0.3924 \text{ (from Table 1)} \\ CR = 263 \text{ (given)}$$

$$\pi_{DT} = \left(\frac{T_{AO} + T_R - T_{AE}}{DT_1}\right)^2 = 2.2196$$

$$CR_1 = 520 \text{ (from Table 1)} \\ T_{AO} = 55 \text{ (given)} \\ T_{Rdefault} = 0 \text{ (from Table 1)} \\ T_{AE} = 14 \text{ (given)} \\ DT_1 = 27.52 \text{ (from Table 1)}$$

$$\lambda_{IND} = 0.3609 \text{ (from Table 1)}$$

$$\lambda_p = (1.0)[(0.1199)(0.8333)(35.23) + (9.575)(1.196)(0.2248) + (0.3924)(0.5058)(2.2196)] + (0.3609)$$

$$\lambda_p = 6.8957 \text{ f/10}^6 \text{ calendar hours}$$

Next Issue

The next issue of the RIAC Journal (2nd Quarter 2008) will present the 217Plus™ connector and resistor failure rate models.

References:

- 1: “An Introduction to the RIAC 217Plus™ Component Failure Rate Models”, Journal of the Reliability Information Analysis Center, First Quarter 2007
- 2: “The 217Plus™ Capacitor and Diode Failure Rate Models”, Journal of the Reliability Information Analysis Center, Second Quarter 2007
- 3: “The 217Plus™ Integrated Circuit and Inductor Failure Rate Models”, Journal of the Reliability Information Analysis Center, Third Quarter 2007
- 4: “The 217Plus™ Transformer and Optoelectronic Device Failure Rate Models”, Journal of the Reliability Information Analysis Center, Fourth Quarter 2007
- 5: Denson, W.K., “Handbook of 217Plus™ Reliability Prediction Models”, Reliability Information Analysis Center (RIAC), 26 May 2006, ISBN 1-933904-02-X
- 6: “An Overview of the 217Plus™ System Reliability Assessment Methodology”, Journal of the Reliability Information Analysis Center, Fourth Quarter 2006

References 1, 2, 3, 4 and 6 available for free download from the RIAC website at <http://theRIAC.org>